

Bright Copper SLOTOCOUP CU 20

Bright Copper SLOTOCOUP CU 20 meets all demands of an electrolyte for copper plating of printed circuit boards (PCB). At perfect metal distribution the electrolyte provides bright, levelling and low-stress copper coatings with excellent elongation at break.

Depending on the task the permissible cathodic current density range is between 1 and 4 A/dm². The electrolyte parameters (copper concentration, electrolyte temperature) can be adapted accordingly. The tendency of a non-uniform metal distribution with increasing cathodic current density applies also to this electrolyte. Therefore the measures of the PCB according to the thickness, diameter of the through holes and pattern geometry must be considered same as the electrode distances of the plant when choosing the current density (see point 2.6).

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read this instruction carefully prior to the use of the process and carefully follow all the parameters that have a direct influence on the operation. We reserve the right to make technical changes. In the interest of safety, please pay attention to the hazard warnings on the labels of the containers. The minimum shelf life of the products is included on the labels and is also available in the appropriate Quality Assurance (QA03).

The current IMDS number of the layer deposited from the process is available on the internet at www.schloetter.com/downloads.

For the storage of chemical products the TRGS 510 must be followed.

If the additives used in this process contain a SVHC-substance, then this will be specified in the corresponding Material Safety Data Sheet, section 15.

